

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application for:

Lam

For: **BOARD LEVEL DECAPSULATOR**

Pre  
2/A Andelt  
10-14-89  
A. Carby

**PRELIMINARY AMENDMENT**

Honorable Commissioner of Patents  
and Trademarks  
Washington, D.C. 20231

Sir:

Please amend the above-identified application as follows:

**IN THE SPECIFICATION**

After the title, please insert - This is a divisional of application Serial No. 08/740,380 filed

Q1 October 29, 1996 A. Patent No. 5932061

SA/9/9/01

**IN THE CLAIMS**

✓ Please cancel claims 1-8.

✓ In Claim 10, line 1, please change "7" to -9--.

✓ Please add the following claims:

Sub 3  
Q2  
1 --11. The method as recited in claim 9, further comprising the step of controlling a flow of  
2 the decapsulation fluid through a pair of tubes that couple an extender to said injection head using a  
3 corresponding pair of valves.

1 12. The method as recited in claim 9, further comprising the step of plugging a stub that  
2 supports the printed circuit board into a substrate of said tray.

Sub B2  
3 13. A method for decapsulating an integrated circuit package that is mounted to a first  
2 surface of a printed circuit board, the printed circuit board having a second surface located below  
3 the first surface of the printed circuit board, comprising the step of: